

**LTM4632 25LD LGA 6.25mm X 6.25mm X 1.82mm (TABLE OF MATERIAL DECLARATION)**

This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.

It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+)  
polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.0367	Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2	0.00685	18.69
					*non-disclosure		
				Continuous Filament Fiber Glass	65997-17-3	0.00608	16.58
				Copper Metal	7440-50-8	0.01902	51.86
				Zinc	7440-66-6	0.00000	0.00
				Chromium(III) oxide	1308-38-9	0.00000	0.00
				Epoxy Resin	*non-disclosure	0.00002	0.06
				Barium Compounds	7727-43-7	0.00121	3.30
				Silica amorphous	7631-86-9	0.00004	0.11
				Calcium caobonate	471-34-1	0.00000	0.01
				Amine compounds	*non-disclosure	0.00002	0.05
				Leveling agent and others	*non-disclosure	0.00005	0.15
				Acrylic Resin	*non-disclosure	0.00231	6.29
				Copper Compounds	147-14-8	0.00001	0.03
				Talc;not containing fibers like asbestos	14807-96-6	0.00014	0.38
				Aromatic carbonyl compounds	*non-disclosure	0.00013	0.36
				Cyanoguanidine	461-58-5	0.00000	0.01
				Nickel	7440-02-0	0.00068	1.85
				Phosphorus	*non-disclosure	0.00005	0.14
				Gold	7440-57-5	0.00003	0.09
				Palladium	7440-05-3	0.00001	0.03
				**Ecotoxic substances	7440-38-2 7439-92-1	0.00001	0.02
				2	Solder Paste	Alloy	0.0033
Antimony (Sb)	7440-36-0	0.00016	5.00				
3	Components	Passive/Active	0.0760	Iron Powder (Fe)	7439-89-6	0.05293	69.65
				Copper (Cu)	7440-50-8	0.01570	20.65
				Nickel (Ni)	7440-02-0	0.00088	1.16
				Tin (Sn)	7440-31-5	0.00065	0.85
				Ceramic (Ba) Compounds	12047-27-7	0.00585	7.69
4	Active Ics	Silicon	0.0024	Silicon (Si)	7440-21-3	0.00240	100.00
5	Wire	Gold	0.0006	Gold (Au)	7440-57-5	0.00062	99.99
7	Encapsulation	Epoxy Resin	0.0931	Fused Silica	60676-86-0	0.07184	77.20
				Epoxy Resin	non-disclosure	0.00828	8.90
				Phenol Resin	non-disclosure	0.00828	8.90
				Crytalline Silica	14808-60-7	0.00279	3.00
				Carbon Black	1333-86-4	0.00047	0.50
				Metal Hydroxide	non-disclosure	0.00140	1.50
Total Package Weight			0.2120				

Note: Composition derived from MSDS and material C of C from Vendors  
Component Weight based on assembly of generic parts